优尚

YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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Product Summary

BV_{DSS}	$R_{DS(ON)\ MAX}$	$I_{D\ MAX}$ T_A = +25°C
60V	38mΩ @ V_{GS} = 10V	6.5A
	47mΩ @ V_{GS} = 4.5V	5.2A

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Power Management Functions
- DC-DC Converters
- Backlighting

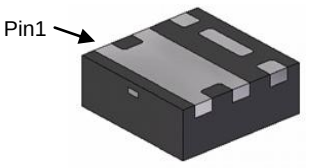
Features and Benefits

- 100% Unclamped Inductive Switch (UIS) Test in Production
- 0.6mm Profile – Ideal for Low Profile Applications
- PCB Footprint of 4mm^2
- Low On-Resistance

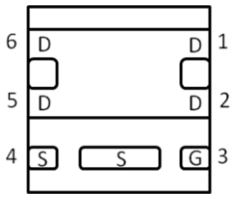
Mechanical Data

- Case: U-DFN2020-6 (Type E)
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 e4
- Weight: 0.0065 grams (Approximate)

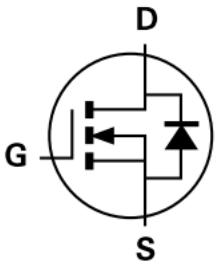
U-DFN2020-6 (Type E)



Bottom View



Pin Out
Bottom View



Equivalent Circuit

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	60	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current (Note 7) V_{GS} = 10V	Steady State	T_A = +25°C T_A = +70°C	I_D	5.3 4.1	A
	t<10s	T_A = +25°C T_A = +70°C	I_D	6.5 5.1	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I_{DM}	30	A
Maximum Body Diode Continuous Current			I_S	2.5	A
Avalanche Current (Note 8) L = 0.1mH			I_{AR}	14.2	A
Avalanche Energy (Note 8) L = 0.1mH			E_{AR}	10	mJ

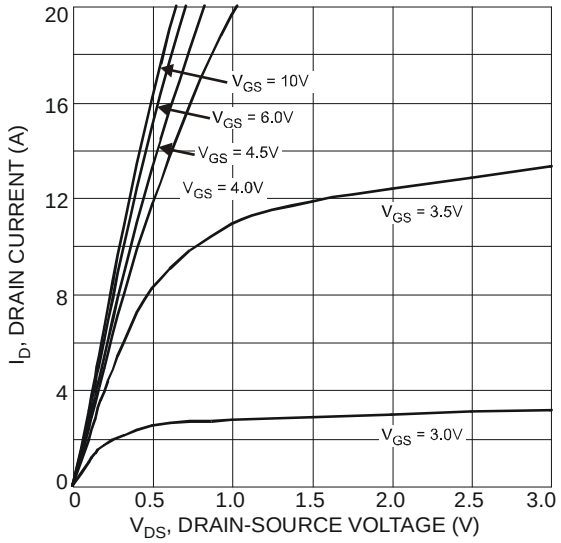
Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	T_A = +25°C	P_D	0.66	W
	T_A = +70°C		0.42	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	189	°C/W
	t<10s		132	
Total Power Dissipation (Note 7)	T_A = +25°C	P_D	2.03	W
	T_A = +70°C		1.31	
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	$R_{\theta JA}$	61	°C/W
	t<10s		43	
Thermal Resistance, Junction to Case (Note 7)		$R_{\theta JC}$	9.3	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV_{DSS}	60	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	100	nA	V_{DS} = 60V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	$V_{GS(TH)}$	1	—	3	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	30	38	mΩ	V_{GS} = 10V, I_D = 4.3A
		—	35	47		V_{GS} = 4.5V, I_D = 4A
Forward Transfer Admittance	$\|Y_{fs}\|$	—	4.5	—	S	V_{DS} = 10V, I_D = 4.3A
Diode Forward Voltage	V_{SD}	—	0.7	1.2	V	V_{GS} = 0V, I_S = 1A
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C_{iss}	—	1287	—	pF	V_{DS} = 25V, V_{GS} = 0V f = 1.0MHz
Output Capacitance	C_{oss}	—	57	—		
Reverse Transfer Capacitance	C_{rss}	—	44	—		
Gate Resistance	R_g	—	1.2	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz
Total Gate Charge (V_{GS} = 10V)	Q_g	—	22.4	—	nC	V_{DS} = 30V, I_D = 4.3A
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	10.4	—		
Gate-Source Charge	Q_{gs}	—	4.9	—		
Gate-Drain Charge	Q_{gd}	—	3.0	—		
Turn-On Delay Time	$t_{D(ON)}$	—	6.6	—	ns	V_{GS} = 10V, V_{DD} = 30V, R_g = 6Ω, I_D = 4.3A
Turn-On Rise Time	t_R	—	8.1	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	20.1	—		
Turn-Off Fall Time	t_F	—	4.0	—		
Body Diode Reverse Recovery Time	t_{RR}	—	18	—	ns	I_S = 4.3A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q_{RR}	—	11.9	—	nC	I_S = 4.3A, dI/dt = 100A/µs

Notes:
6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
8. I_{AR} and E_{AR} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
9. Short duration pulse test used to minimize self-heating effect.
10. Guaranteed by design. Not subject to product testing.



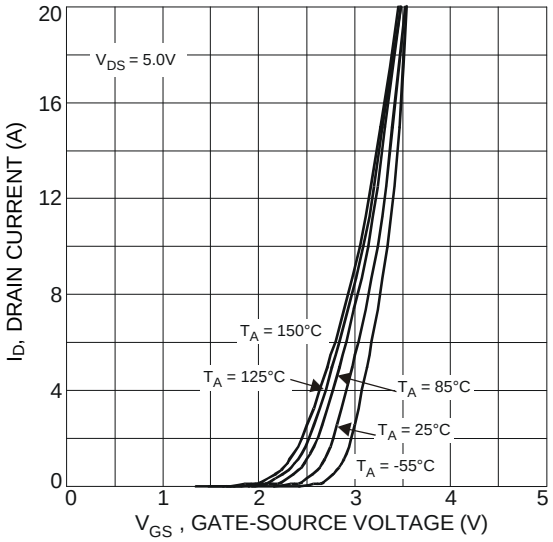


Fig. 2 Typical Transfer Characteristics

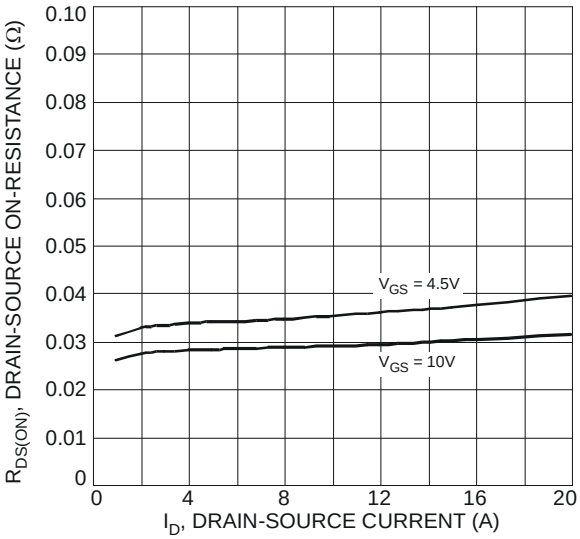


Fig. 3 Typical On-Resistance vs.
Drain Current and Gate Voltage

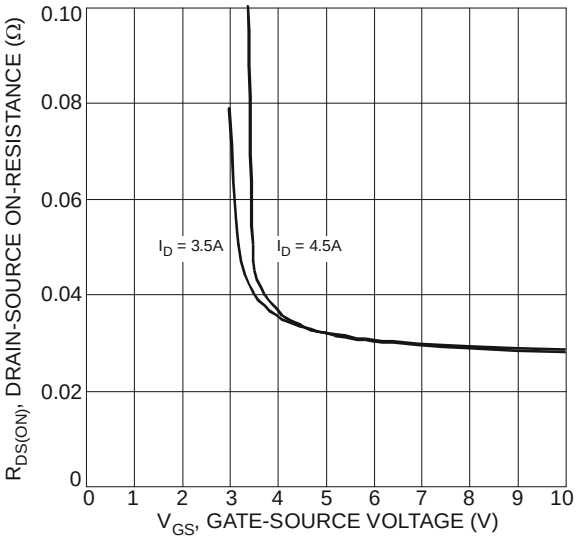


Fig. 4 Typical On-Resistance vs.
Drain Current and Gate Voltage

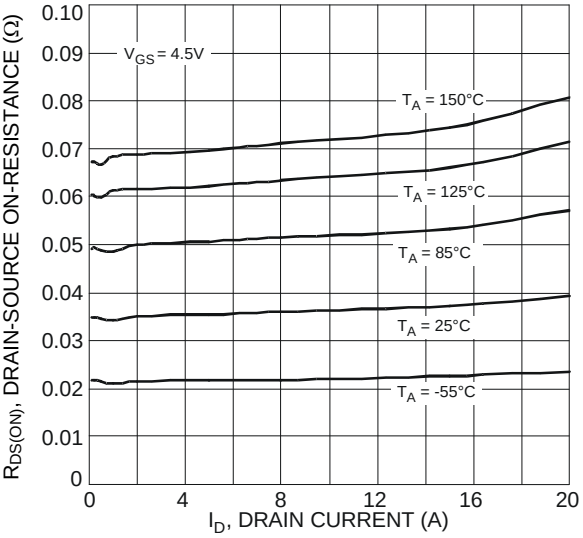


Fig. 5 Typical On-Resistance vs.
Drain Current and Temperature

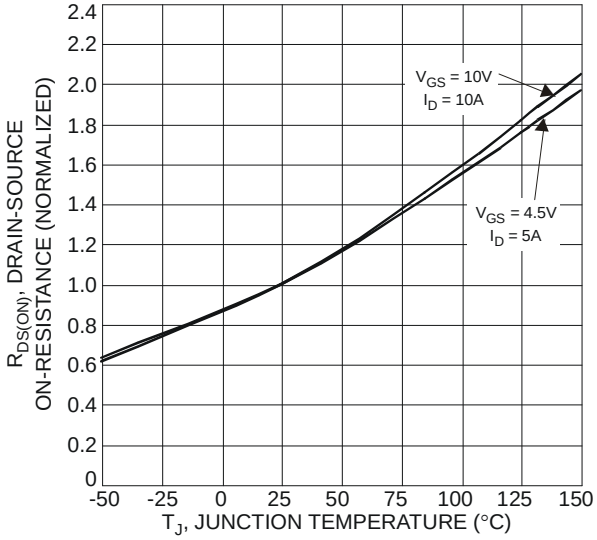


Fig. 6 On-Resistance Variation with Temperature

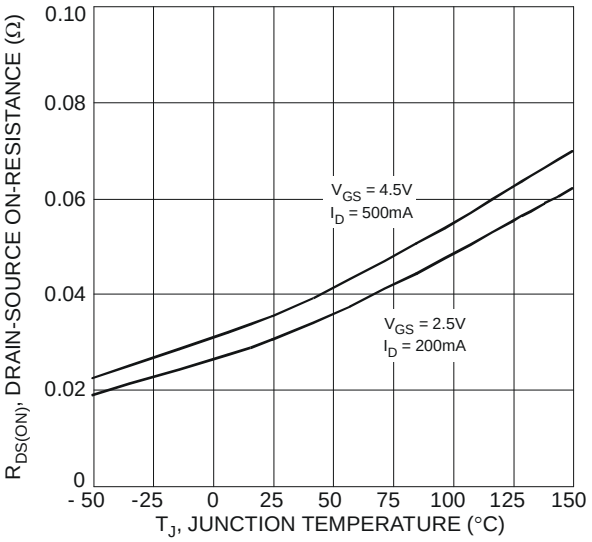


Fig. 7 On-Resistance Variation with Temperature

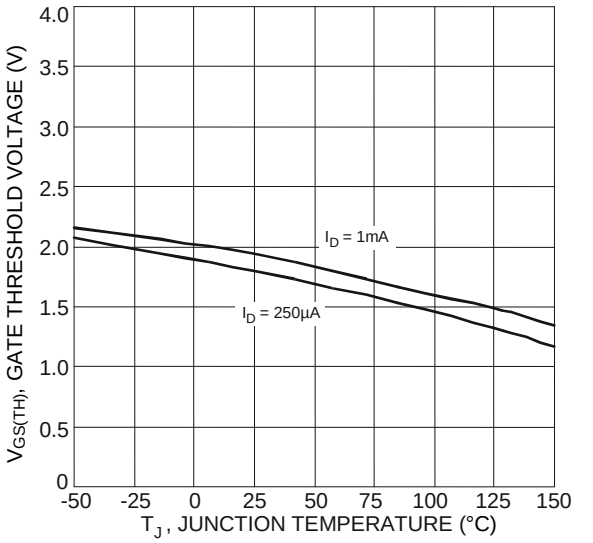


Fig. 8 Gate Threshold Variation vs. Junction Temperature

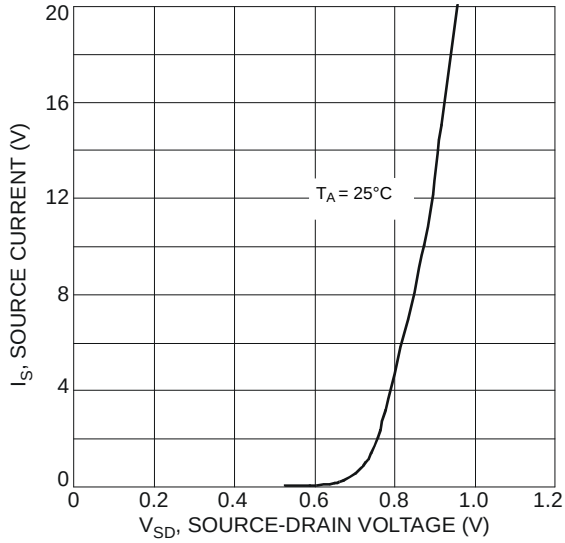


Fig. 9 Diode Forward Voltage vs. Current

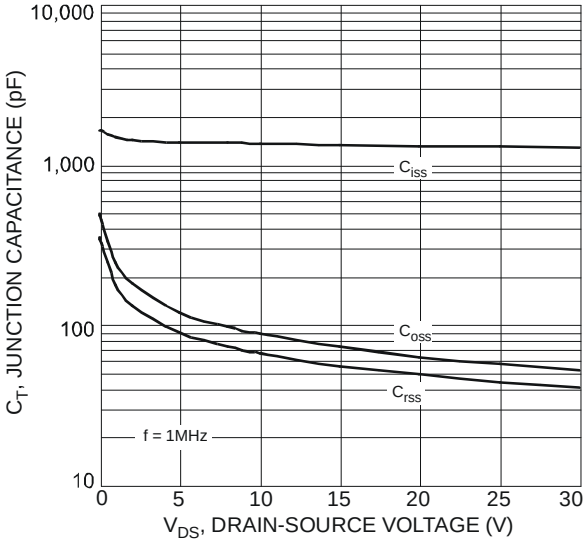


Fig. 10 Typical Junction Capacitance

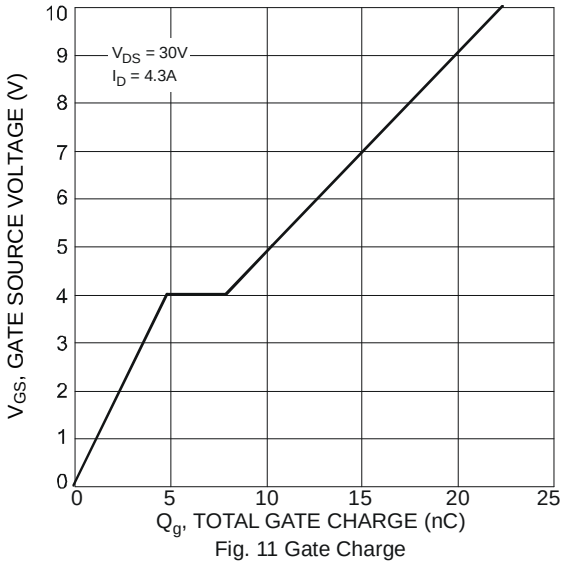


Fig. 11 Gate Charge

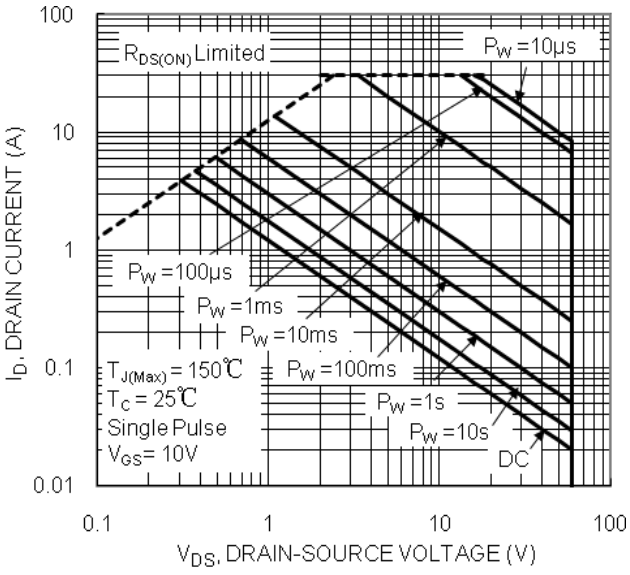


Fig 12. SOA, Safe Operation Area

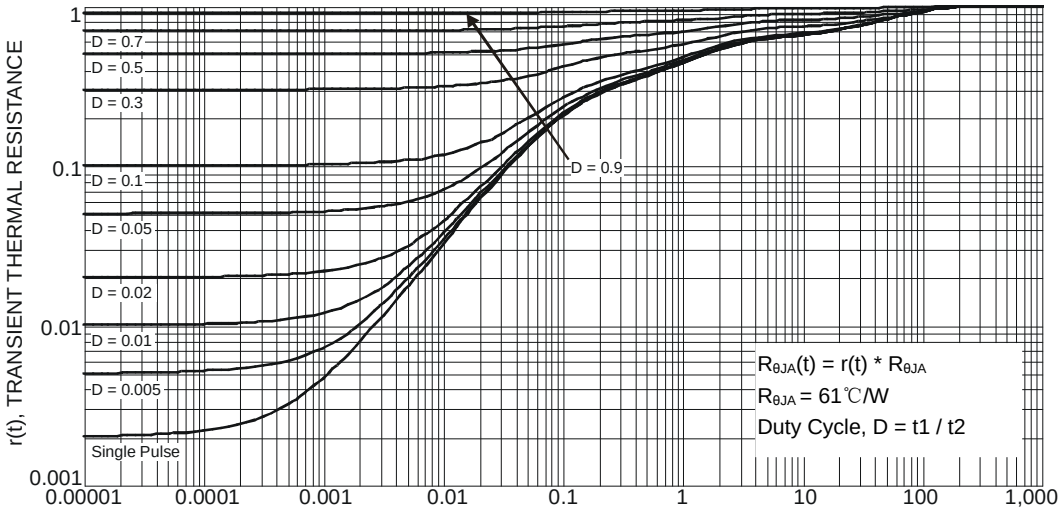
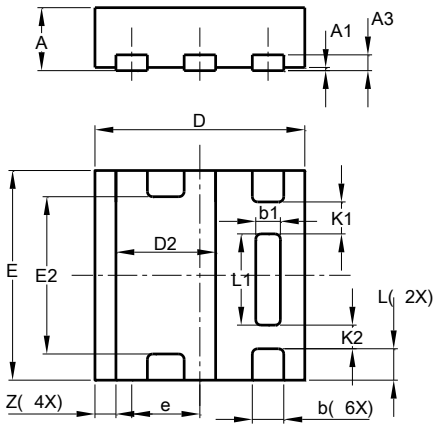


Fig. 13 Transient Thermal Resistance

Package Outline Dimensions

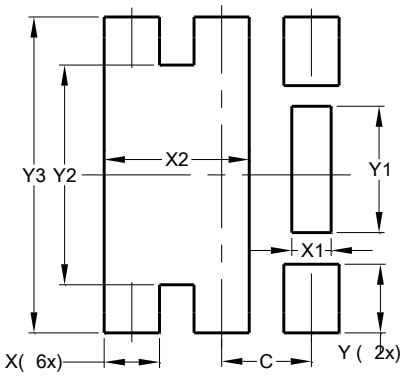
U-DFN2020-6 (Type E)



U-DFN2020-6 (Type E)			
Dim	**Min**	**Max**	**Typ**
A	0.57	0.63	0.60
A1	0	0.05	0.03
A3	–	–	0.15
b	0.2	0.35	0.30
b1	0.185	0.285	0.235
D	1.95	2.05	2.00
D2	0.85	1.05	0.95
E	1.95	2.05	2.00
E2	1.40	1.60	1.50
e	–	–	0.65
L	0.25	0.35	0.30
L1	0.82	0.92	0.87
K1	–	–	0.305
K2	–	–	0.225
Z	–	–	0.20
All Dimensions in mm			

Suggested Pad Layout

U-DFN2020-6 (Type E)



Dimensions	Value (in mm)
C	0.650
X	0.400
X1	0.285
X2	1.050
Y	0.500
Y1	0.920
Y2	1.600
Y3	2.300